MATERIAL DECLARATION SHEET

Package Type	TBU-DT		
Product Line	Semiconductor Products		
Compliance Date	November 16, 2017		
RoHS Compliant	Yes	MSL	1

No.	Construction Element (Subpart)	Homogeneous Material	Material Weight [g]	Homogeneous Material\ Substances	CAS Number if applicable	Materials Mass %	Material Mass % of Total Unit Weight	Subpart Mass of Total Wt. (%)
1	Encapsulation	Epoxy resin	0.030757	Epoxy Resin	Trade Secret	6	2.4557	40.929
				Phenol Resin	Trade Secret	3	1.2279	
				Silica fused	60676-86-0	90.45	37.0204	
				Carbon Black	1333-86-4	0.55	0.2250	
2	Leadframe	Copper alloy	0.036625	Copper	7440-50-8	96	37.209	48.738
				Iron	7439-89-6	2.2	0.853	
				Zinc	7440-66-6	0.1	0.039	
				Phosphorous	7723-14-0	0.075	0.029	
				Lead (impurity)	7439-92-1	0.001	0.0004	
				Silver (Plating)	7440-22-4	1.624	0.6295	
3	Chip	Silicon	0.004144	Silicon	7440-21-3	100	10.659	5.515
4	Die Attach	Conductive Silver Epoxy	0.001362	Silver	7440-22-4	93.4	1.693	1.812
				Epoxy resin	Trade Secret	5.5	0.100	
				Polymeric compound	Trade Secret	0.55	0.0099	
				Functionalized Ester	Trade Secret	0.55	0.0099	
5	Bond wires	Gold	0.000134	Gold	7440-57-5	99.99	0.17798	0.178
				Potential impurities may include Ag, Be or Ca ≤ 30 ppm	7440-22-4; 7440-41-7; 7440-70-2	0.01	0.00002	

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6	Terminal Finish	Alloy	0.002125	Tin	7440-31-5	100.00	2.828	2.828
		Total Weight	0.075147					

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